AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (ORIGINAL) A cover sheet package comprising:

a thin film cover sheet including a resin film, the thin film cover sheet having an adhesive film formed on one side surface of the resin film, and which is adhered via the adhesive film to a recording surface of a disk substrate of an optical disk;

a peeling sheet which is peelably adhered on a surface of the adhesive film of the cover sheet and which is peeled before the cover sheet is adhered to the recording surface of the disk substrate; and

a protective sheet which is peelably adhered on a surface of the resin film of the cover sheet,

wherein, when an adhesive force for adhering the peeling sheet to the adhesive film of the cover sheet is indicated by AP_1 and an adhesive force for adhering the protective sheet to the resin film of the cover sheet is indicated by AP_2, the peeling sheet is adhered to the adhesive film of the cover sheet and the protective sheet is adhered to the resin film of the cover sheet so that the relationship $AP_1 \leq AP_2$ is satisfied.

2. (ORIGINAL) A cover sheet package according to claim 1, wherein the adhesive force AP_1 is set to be a value selected from a range of 5 to 50 (gf/cm), and the adhesive force AP_2 is set to be a value selected from a range of $(AP_1 \times 1.0)$ to $(AP_1 \times 3.0)$.

3. (ORIGINAL) A cover sheet package according to claim 2, wherein a total thickness of the cover sheet, the resin film and the adhesive film is a value in a range from 80 μm to 110 μm.

4. (WITHDRAWN) A method of manufacturing a cover sheet package, the method comprising:

preparing a laminated sheet material which has a resin film, an adhesive film, a peeling sheet and a protective sheet;

cutting the protective sheet, the resin film and the adhesive film;

forming an opening by punching the protective sheet, the resin film and the adhesive film in an annular configuration, cutting annular configuration portions thereof away from other portions thereof, and punching the peeling sheet at a center circle of the annular configuration;

forming the resin film and the adhesive film into a cover sheet to be adhered to a disk substrate; and

adhering the peeling sheet to the adhesive film of the cover sheet and the protective sheet to the resin film of the cover sheet so that the relationship $AP_1 \leq AP_2$ is satisfied when AP_1 indicates an adhesive force for adhering the peeling sheet to the adhesive film of the cover sheet and AP_2 indicates an adhesive force for adhering the protective sheet to the resin film of the cover sheet.

5. (WITHDRAWN) A method of manufacturing a cover sheet package according to claim 4, further comprising:

setting the adhesive force AP_1 to a value selected from a range of 5 to 50 (gf/cm); and

setting the adhesive force AP_2 to a value selected from a range of $(AP_1 \times 1.0)$ to $(AP_1 \times 3.0)$.

6. (WITHDRAWN) A method of manufacturing a cover sheet package according to claim 5, further comprising:

adjusting a total thickness of the cover sheet, the resin film and the adhesive film to a value in a range from 80 μm to 110 μm.

7. (WITHDRAWN) A method of manufacturing a cover sheet package comprising:

preparing a laminated sheet material which has a resin film, an adhesive film, a peeling sheet and a protective sheet;

cutting the resin film, the adhesive film and the peeling sheet;

forming the resin film and the adhesive film into a cover sheet to be adhered to a disk substrate;

forming an opening at a center of the laminated sheet by punching the peeling sheet and the cover sheet in a disk configuration, cutting disk configuration portions thereof away from other portions thereof, and punching the protective sheet at the center of the laminated sheet; and

adhering the peeling sheet to the adhesive film of the cover sheet and the protective sheet to the resin film of the cover sheet so that the relationship $AP_1 \leq AP_2$ is satisfied when AP_1 indicates an adhesive force for adhering the peeling sheet to the adhesive film of the cover sheet and AP_2 indicates an adhesive force for adhering the protective sheet to the resin film of the cover sheet.

8. (WITHDRAWN) A method of manufacturing a cover sheet package according to claim 7, further comprising:

setting the adhesive force AP_1 to a value selected from a range from 5 to 50 (gf/cm); and

setting the adhesive force AP_2 to a value selected from a range from ($AP_1 \times 1.0$) to ($AP_1 \times 3.0$).

9. (WITHDRAWN) A method of manufacturing a cover sheet package according to claim 8, further comprising:

adjusting a total thickness of the cover sheet, the resin film and the adhesive film to a value in a range from 80 μm to 110 μm.

10. (NEW) The cover sheet package of claim 2, wherein peeling material including silicone is coated on an attaching surface of the peeling sheet.

11. (NEW) The cover sheet package of claim 4, wherein adhesive material including vinyl acetate is coated on an attaching surface of the protective sheet.

12. (NEW) A method of producing an optical disk using the cover sheet package of claim 1.